



BME288 Breakout Board

BOARD CHARACTERISTICS

Copper Layer Count: 4 Board Thickness: 1.5900 mm

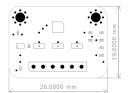
Board overall dimensions: 26.1000 mm x 19.1000 mm

Min track/spacing: 0.2000 mm / 0.0000 mm Min hole diameter: 0.3000 mm

Copper Finish: HAL lead—free Impedance Control: No Castellated pads: No Plated Board Edge: No

Edge card connectors: No

	Layer Name	Туре	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
	F.Silkscreen	Top Silk Screen	Not specified	0 mm	White	1	0
	F.Paste	Top Solder Paste		0 mm		1	0
	F.Mask	Top Solder Mask	Not specified	0.01 mm	Black	3.3	0
	F.Cu	copper		0.035 mm		1	0
	Dielectric 1	prepreg	FR4	0.2 mm		4.5	0.02
D	GND	copper		0.0175 mm		1	0
	Dielectric 2	core	FR4	1.065 mm		4.5	0.02
	+3.3	copper		0.0175 mm		1	0
	Dielectric 3	prepreg	FR4	0.2 mm		4.5	0.02
	B.Cu	copper		0.035 mm		1	0
	B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Black	3.3	0
	B.Paste	Bottom Solder Paste		0 mm		1	0
	B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	White	1	0



TTN SMARTHAR ZZ					
Title: BME688 Breakout Board					
	Rev: 1.5				
	TTN SMART				